For use with Surface Mount packages

Part Number - 7109DG

Recommended copper pad size for heat sink and device mounting footprint

Thermal Curves

| Thermal Resistance | 11.00 |

Thermal resistance value is based on a 75°C rise in natural convection
Product Information

Packaged in tape and reel for automated assembly
Look up tape and reel dimensions

<table>
<thead>
<tr>
<th>Part #</th>
<th>Description</th>
<th>Finish</th>
<th>Board Mounting</th>
</tr>
</thead>
<tbody>
<tr>
<td>7109DG</td>
<td>Surface mount heat sink for D2 Pak (TO-263) package semiconductors</td>
<td>Matte Tin Plated</td>
<td>N/A</td>
</tr>
</tbody>
</table>

This non-electronic component is functionally unaffected by the normal soldering or reflow processes used for semiconductor circuits. The heat resistance time or heat resistance temperature is not applicable for the component.

Not Exactly what you need?

We offer several options for those applications which require a more unique solution. For slight modifications of this part or other attachment options, finishes, and interface materials, contact your local representative. Challenge us with your thermal requirements - we can design custom solutions.

For technical help with our Standard Products, please call (603) 224-9988, or contact your Aavid Sales Rep

Email: info@aavid.com

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